

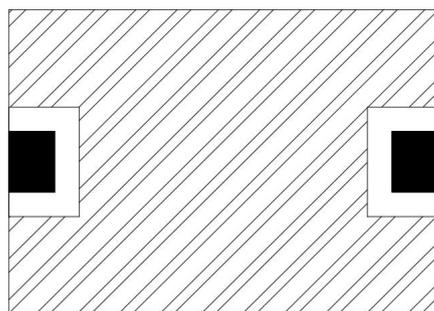
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

NO.	Parameter	Frequency (MHz)	SPC		
			Min.	Typ.	Max.
1	Insertion Loss (dB)	940~1230			1.8
2	Ripple (dB)	940~1230			1.0
3	VSWR	940~1230			1.8
4	Attenuation (dBC)	DC~750	40		
		1380~2000	40		
5	In/Output Impedance (Ω)		50		
6	Power		5W		
Operating & Storage Condition (Component)					
Operation Temperature Range: -55°C ~ +85°C					
Storage Temperature Range: -55°C ~ +85°C					
Storage Condition before Soldering (Included packaging material)					
Storage Temperature Range: +5 ~ +40 °C					
Humidity: 30 to 70% relative humidity					

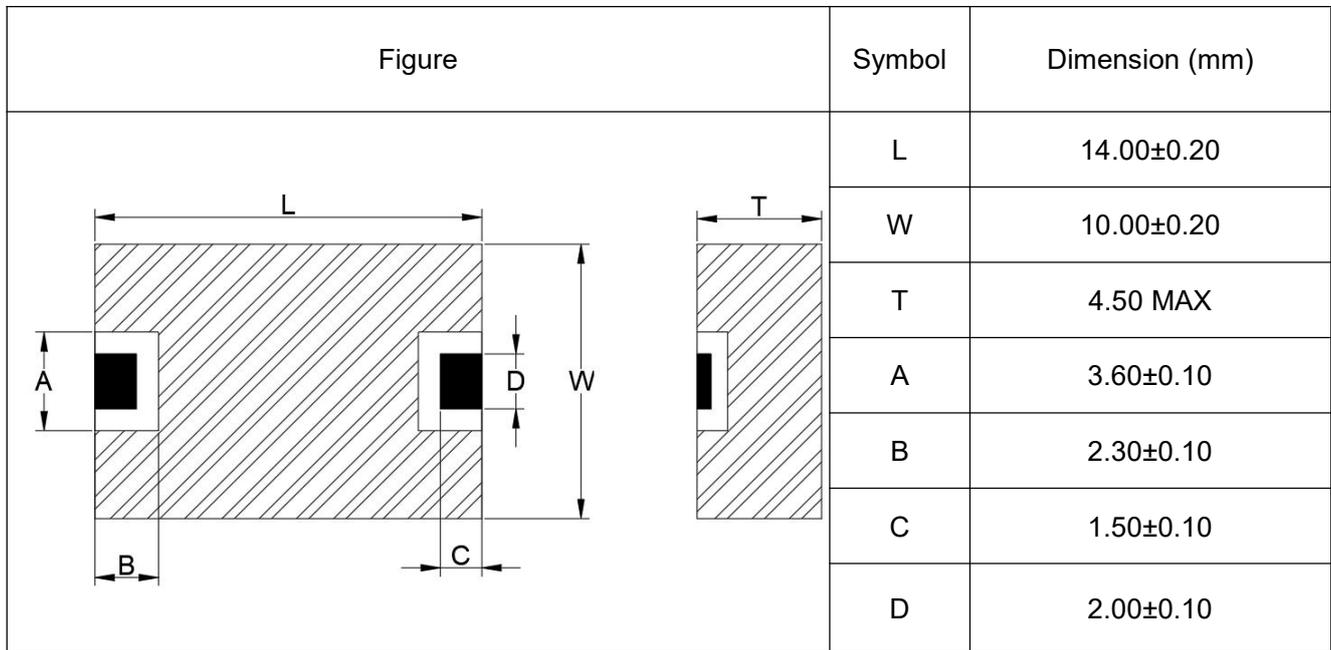
Construction



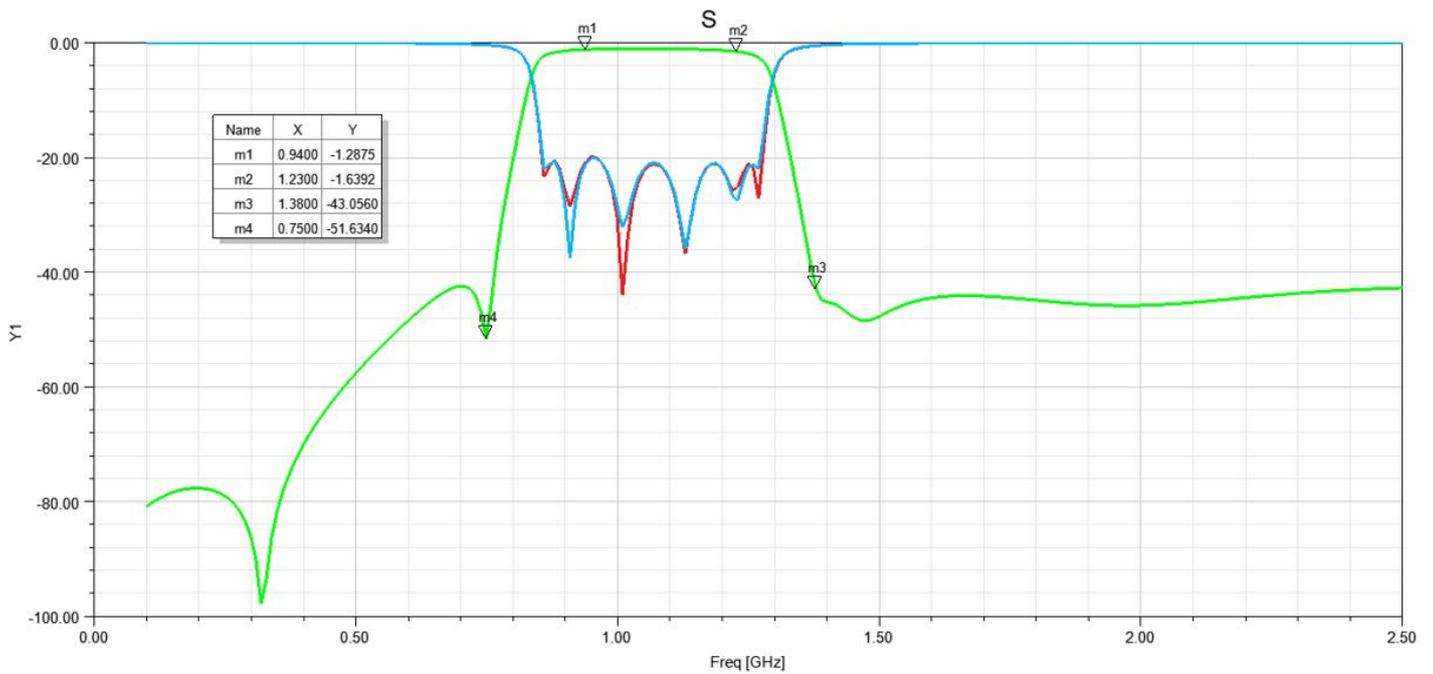
 I/O Port

 GND

Dimensions



Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.